

ON Semiconductor				10/15/2019	
Base Part		74LCX126	HF	Pb-free	
Orderable Part		74LCX126MX	Total weight (mg)	155.775	
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight	
Die	3.63	Silicon (Si)	7440-21-3	100	
Die Attach	0.367	Silver (Ag)	7440-22-4	78.5	
		Phenolic Resin-2	54208-63-8	21.5	
Lead Frame	68.71	Silver (Ag)	7440-22-4	0.02183088	
		Zinc (Zn)	7440-66-6	0.12516373	
		Iron (Fe)	7439-89-6	2.34900306	
		Copper (Cu)	7440-50-8	97.42250036	
		Phosphorus (P)	7723-14-0	0.08150196	
Mold Compound-Black	81.974	Ortho Cresol Novolac Resin	29690-82-2	20.00024398	
		Carbon Black (C)	1333-86-4	1.00031717	
		Fused Silica (SiO2)	60676-86-0	78.99943885	
Plating	0.944	Palladium (Pd)	7440-05-3	3.60169492	
		Nickel (Ni)	7440-02-0	94.38559322	
		Gold (Au)	7440-57-5	2.01271186	
Wire Bond - Cu	0.15	Copper (Cu)	7440-50-8	100	
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>					